

## Electronic Patent Application Fee Transmittal

Application Number:	10055266			
Filing Date:	22-Jan-2002			
Title of Invention:	Semiconductor package having changed substrate design using special wire bonding			
First Named Inventor/Applicant Name:	Ki-won Choi			
Filer:	Alexander Charles Johnson/Li mei Vermilya			
Attorney Docket Number:	9898-208			
Filed as Large Entity				
<b>Utility Filing Fees</b>				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
<b>Extension-of-Time:</b>				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
Request for continued examination	1801	1	790	790
<b>Total in USD (\$)</b>				<b>790</b>